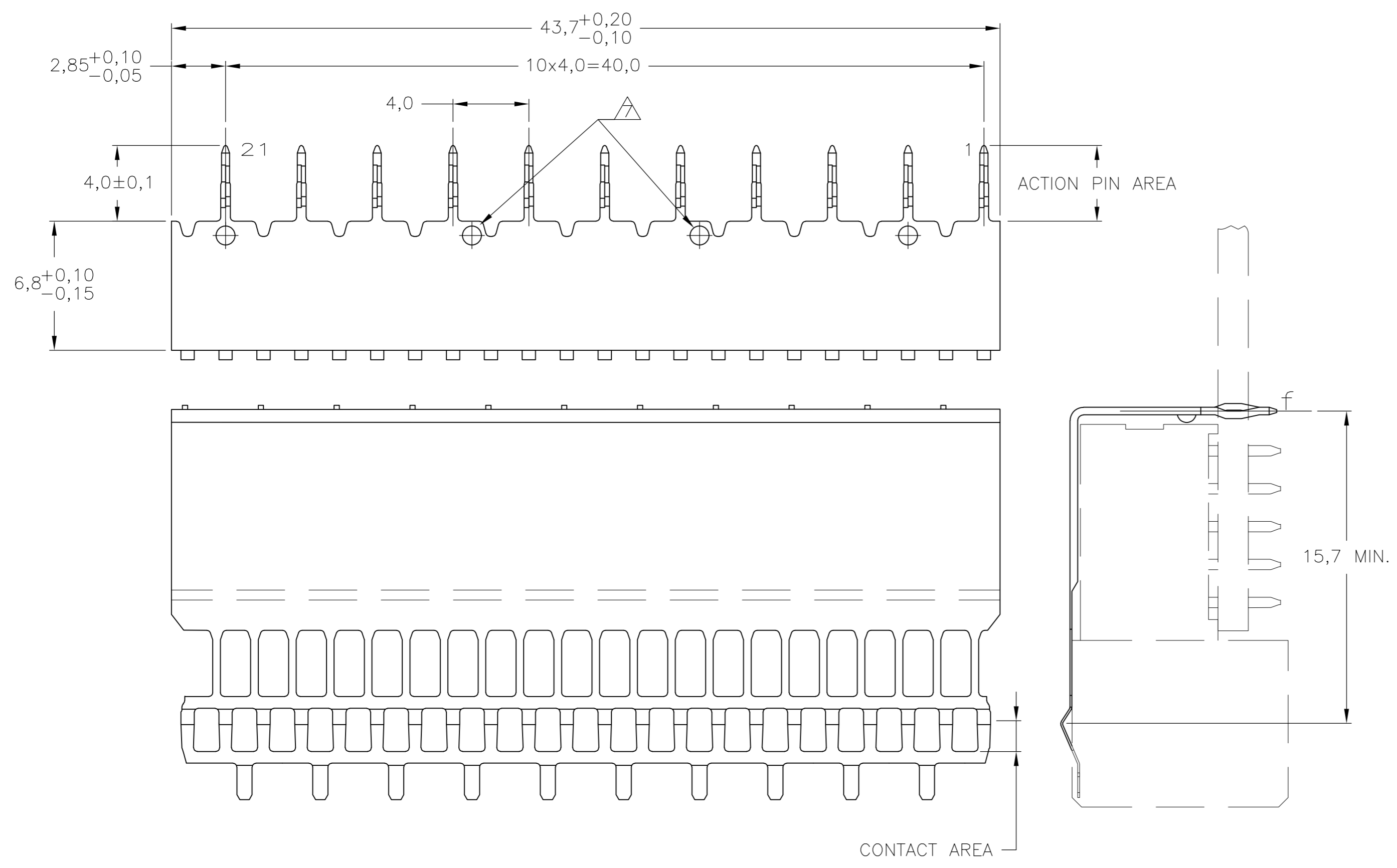
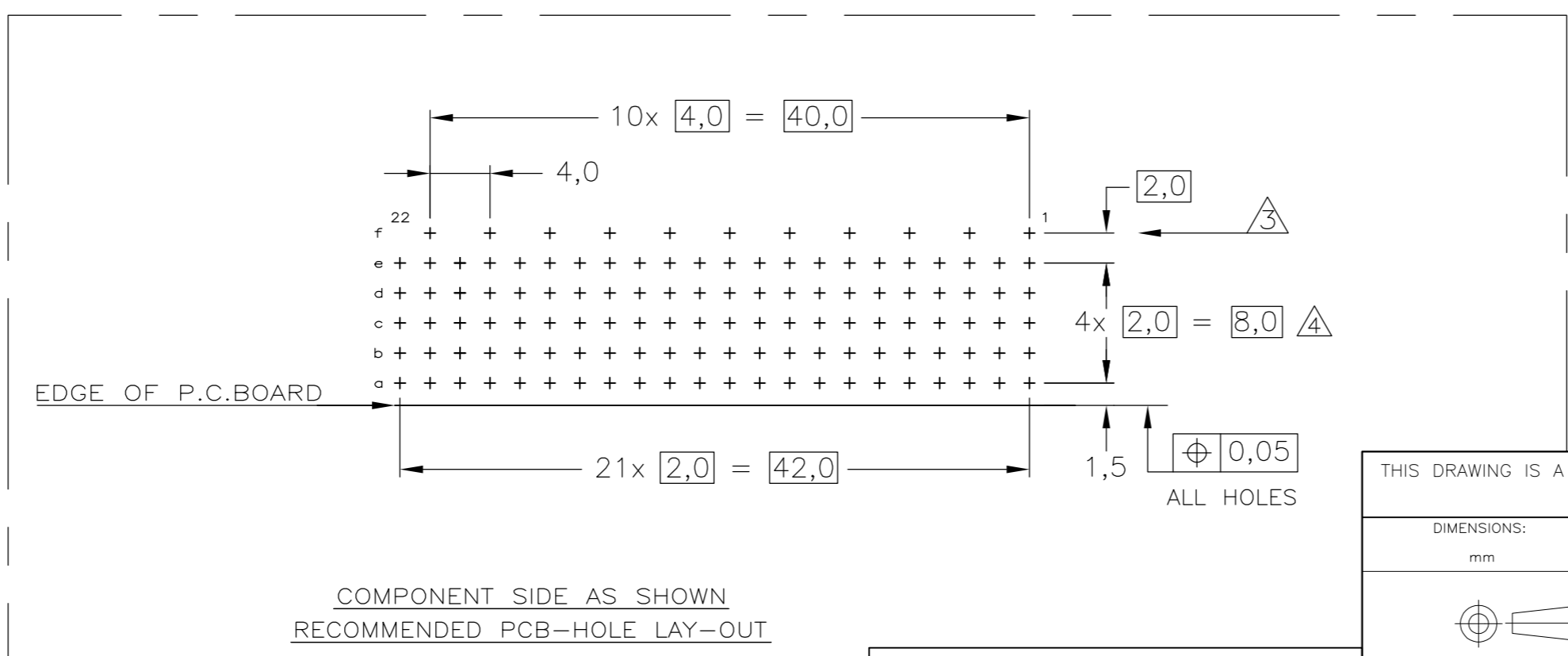


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LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD		
ES	-	K	REVISED PER ECO-13-015151	17DEC2013	FL	FY	



- NOTES:
- △ GENERAL PLATING SPECIFICATION: UNDERPLATING (ENTIRE CONTACT): 1,27µm NICKEL MIN.AND ACTION PIN: 0,5µm TIN-LEAD MIN. FOR PLATING OF MATING SURFACES SEE PERFORMANCE LEVEL SHOWN IN PART NUMBER TABLE.
 - △ MATERIAL; PHOSPHORBRONZE.
 - △ ROW "f" 11 PLATED THROUGH HOLES FOR UPPERSHIELD
 - △ HOLE PATTERN FOR FEMALE CONNECTOR TYPE B-22
 - △ COLUMNS 110 PLATED-THROUGH HOLES AT 2x2mm SQUARE GRID
 - △ SHIELDS LUBRICATED WITH BELLCORE APPROVED LUBRICANT. TECHNICAL REF: TR-NWT-001217 ISSUE 1, SEPT. 1992.
 - △ GENERAL PLATING SPECIFICATION: UNDERPLATING (ENTIRE CONTACT): 1,27µm NICKEL MIN.AND ACTION PIN: 0,5µm TIN-LEAD MIN. ASTM B579 60/40 FOR PLATING OF MATING SURFACES SEE PERFORMANCE LEVEL SHOWN IN PART NUMBER TABLE.
 - △ OPTIONAL DIMPLES AT DISCRETION OF DIE ENGINEER.
 - △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI
 - △ CONFORMS TO ALL TESTING ACCORDING IEC 61076-4-101 PERFORMANCE LEVEL 2.
 - △ CONFORMS TO ALL TESTING ACCORDING IEC 61076-4-101 PERFORMANCE LEVEL 1.
 - △ CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA GR-1217-CORE QUALITY LEVEL III,CENTRAL OFFICE APPLICATIONS.
 - △ 0.76µm MIN GOLD PLATING AT MATING SURFACE.
 - △ 1.27µm MIN GOLD PLATING AT MATING SURFACE.



P.C.B. HOLE DIM. ACTION PIN
 FOR DETAILS SEE
 APPLICATION SPECIFICATION

FINISH	MATERIAL	PARTNUMBER
1 9 12	2	8-352151-4
1 13	2	9-352151-3
6 5 11	2	9-352151-1
1 5 11	2	352151-9
1 9	2	352151-2

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DWN	W. v.d.HEIJDEN	17-01-97
CHK	W. v.d.HEIJDEN	17-01-97
APVD	F. v.KONINGSBRUGGE	-
PRODUCT SPEC	108-19082	
APPLICATION SPEC	114-19029	
WEIGHT	-	
CUSTOMER DRAWING		

TE Connectivity

Z-PACK 2mm HM
 FEMALE GROUND RETURN UPPER SHIELD
 TYPE B-22 COLUMNS

SIZE	A2	CAGE CODE	00779	DRAWING NO	C=352151	RESTRICTED TO	-
SCALE	5:1	SHEET	1 of 1	REV	K		